

# ADHESIVE SELECTOR

Specific data and guidelines should be obtained from the respective manufacturer.

	<b>Contact Adhesive</b>	<b>Urea Adhesive</b>	<b>Hot Melt Adhesive</b>	<b>Resocinol Resin Adhesive</b>	<b>Epoxy Adhesive</b>	<b>Polyvinyl Acetate Resin Adhesive (PVA)</b>
<b>Description</b>	A neoprene or rubber base adhesive. Will bond if both surfaces are coated with the adhesive. Solvent and water base types available.	Urea formaldehyde adhesives are satisfactory for most applications. They can be used for room temperature bonding or for hot bonding. When hot bonding, the temperature should not exceed 85°C (185°F) for best results.	An adhesive that is suitable for edgebanding because of their low heat resistance. The particular grade adhesive chosen should have a minimum softening point of 65°C (150°F).	These adhesives are recommended when moisture, chemical and heat resistance are required. They may be used in either hot pressing or room temperature bonding. Resocinol can be used with fire rated and chemical resistant laminates.	Epoxy adhesives are liquids with no volatile components.	PVA emulsion adhesives may be used for laminates to wood substrates where resistance to moisture and high heat are not required in the application.
<b>Applications</b>	Suitable for flatwork and postformed work. Bonding decorative laminate to particleboard and most substrates. Also good for bonding dissimilar or non-porous materials.	For flatwork and postformed work. Bonding decorative laminate to particleboard.	Suitable for use only in edgebanding operations.	For flatwork, simple postformed COVED work, and bonding decorative laminate to particleboard.	For bonding decorative laminate to impervious cores such as steel.	For flatwork, simple postforming COVED work, and bonding decorative laminate to particleboard.
<b>Influence on Substrate</b>	Minimum telegraphing of substrate surface imperfections.	Moderate telegraphing of substrate surface imperfections.	Minimum telegraphing of substrate surface imperfections.	Maximum telegraphing of substrate surface imperfections	Minimum telegraphing of substrate surface imperfections	Moderate telegraphing of substrate surface imperfections. Tends to contribute to grain or particle "raising".

## Recommendations for bonding assemblies

- The surface to be bonded should be clean and dry. Ensure sufficient adhesive is applied to either or both sides of the surface to be bonded, and that the appropriate pressure is applied over the entire area to be bonded. Pinch rollers or heavy weighted rollers are ideal, however, hand held rollers such as a “j” roller can be used. The “j” roller should be made of steel or hard solid rubber (50-80 durometer) and not over 3 inches (75 mm) wide.